FOR IMMEDIATE RELEASE

Agency Contact:
David Moreno
Open Sky Communications
Tel: +1-415-519-3915
E-mail: dmoreno@openskypr.com

EBEAM INITIATIVE MARKS 15 YEAR ANNIVERSARY

FUJIFILM Corporation Joins the eBeam Initiative

SAN JOSE, Calif., February 27, 2024—The eBeam Initiative, a forum dedicated to the education and promotion of new semiconductor manufacturing approaches based on electron beam (eBeam) technologies, today marks its 15-year anniversary at an annual meeting being held in conjunction with the SPIE Advanced Lithography + Patterning Conference in San Jose. FUJIFILM Corporation will be recognized at the event as the newest member joining more than 50 companies in the eBeam Initiative.

The eBeam Initiative also announces the publication of its fourth annual Deep Learning (DL) survey of its members' products and applications using DL in the photomask-to-wafer manufacturing flow. The complete list of DL applications from 15 member companies can be found at www.ebeam.org.

"Over the 15-year history of the eBeam Initiative, all members have worked together to educate and promote the contributions of the mask industry to the semiconductor industry and to technology," stated Aki Fujimura, CEO of D2S, the managing company sponsor of the eBeam Initiative. "We welcome FUJIFILM Corporation to the eBeam Initiative. As our first member from the chemical supply chain, they will bring much needed expertise on advances in resist technologies to our collective efforts."

Added Fujimura, "Deep learning is essential now in semiconductor manufacturing. Both DL and curvilinear manufacturing, a significant trend in both the EUV and 193i lithography segments, are greatly improved through computation in the pixel space. Solutions in the pixel space benefit greatly in performance from GPU acceleration. These three trends – DL, curvilinear and GPU acceleration – will be our focus as we look at the eBeam Initiative's educational agenda for this year."

About The eBeam Initiative

The eBeam Initiative provides a forum for educational and promotional activities regarding new semiconductor manufacturing approaches based on electron beam (eBeam) technologies. The goals of the Initiative are to reduce the barriers to adoption to enable more integrated circuit (IC) design starts and faster time-to-market while increasing the investment in eBeam technologies throughout the semiconductor ecosystem. Members, which span the semiconductor ecosystem, include: aBeam Technologies; Advantest; Alchip Technologies; AMD; AMTC; Applied Materials; Artwork Conversion; ASML; Cadence Design Systems; Canon; CEA-Leti; D2S; Dai Nippon Printing; EQUIcon Software GmbH Jena; ESOL; EUV Tech; Fractilia; Fraunhofer IPMS; FUJIFILM Corporation; Fujitsu Semiconductor Limited; GenISys GmbH; GlobalFoundries (GF); Grenon Consulting; Hitachi High-Tech Corporation; HJL Lithography; HOLON CO., LTD; HOYA Corporation; IBM; imec; IMS CHIPS; IMS Nanofabrication AG; JEOL; KIOXIA; KLA; Micron Technology; Multibeam Corporation; NCS; NuFlare Technology; Petersen Advanced Lithography; Photronics; QY Mask; Samsung Electronics; Semiconductor Manufacturing International (Shanghai) Corporation (SMIC); Siemens EDA; STMicroelectronics; Synopsys; TASMIT; Tokyo Electron Ltd. (TEL); TOOL Corporation; Toppan Photomask Corporation; UBC Microelectronics; Vistec Electron Beam GmbH and ZEISS. Membership is open to all companies and institutions throughout the electronics industry. To find out more, please visit www.ebeam.org.

###